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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220,I <sup>2</sup> PAK, D <sup>2</sup> PAK,DPAK,IPAK	TO-220FP	
V <sub>DS</sub>	Drain-source voltage (V <sub>GS</sub> = 0)	600		V
V <sub>GS</sub>	Gate-source voltage	± 25		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	10	10 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	6.3	6.3 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	40	40 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	90	25	W
	Derating factor	0.8	0.2	W/°C
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	15		V/ns
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T <sub>C</sub> = 25 °C)		2500	V
T <sub>stg</sub>	Storage temperature	-55 to 150		°C
T <sub>J</sub>	Max. operating junction temperature	150		°C

1. Limited only by maximum temperature allowed
2. Pulse width limited by safe operating area
3. I<sub>SD</sub> ≤ 10 A, di/dt ≤ 400 A/μs, V<sub>DD</sub> = 80% V<sub>(BR)DSS</sub>

**Table 3. Thermal data**

Symbol	Parameter	Value						Unit
		TO-220	I <sup>2</sup> PAK	DPAK	D <sup>2</sup> PAK	IPAK	TO-220FP	
R <sub>thj-case</sub>	Thermal resistance junction-case max	1.38					5	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-amb max	62.5				100	62.5	°C/W
R <sub>thj-pcb</sub>	Thermal resistance junction-pcb max			50	30			°C/W
T <sub>I</sub>	Maximum lead temperature for soldering purposes	300						°C

**Table 4. Avalanche characteristics**

Symbol	Parameter	Max value	Unit
I <sub>AS</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>J</sub> max)	3.5	A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> = I <sub>AS</sub> , V <sub>DD</sub> = 50 V)	200	mJ

## 2 Electrical characteristics

(T<sub>CASE</sub>=25 °C unless otherwise specified)

**Table 5. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0	600			V
dv/dt <sup>(1)</sup>	Drain-source voltage slope	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V	45			V/ns
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max rating, V <sub>DS</sub> =Max rating, T <sub>c</sub> =125 °C			1 10	μA μA
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A		0.37	0.45	Ω

1. Characteristic value at turn off on inductive load

**Table 6. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 5 A		7.5		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>DS</sub> = 50 V, f = 1 MHz, V <sub>GS</sub> = 0		850 44 5		pF pF pF
C <sub>oss eq.</sub> <sup>(2)</sup>	Equivalent output capacitance	V <sub>GS</sub> = 0, V <sub>DS</sub> = 0 to 480 V		130		pF
R <sub>g</sub>	Gate input resistance	f = 1 MHz Gate DC Bias = 0 Test signal level = 20 mV open drain		3.7		Ω
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total gate charge Gate-source charge Gate-drain charge	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 10 A V <sub>GS</sub> = 10 V <i>Figure 19</i>		31 4.2 15.9		nC nC nC

1. Pulsed: pulse duration = 300 μs, duty cycle 1.5%

2. C<sub>oss eq.</sub> is defined as a constant equivalent capacitance giving the same charging time as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 5\text{ A}$ ,		22		ns
$t_r$	Rise time	$R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$		18.5		ns
$t_{d(off)}$	Turn-off delay time	<i>Figure 18</i>		50		ns
$t_f$	Fall time	<i>Figure 23</i>		12		ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current				10	A
$I_{SDM}$	Source-drain current (pulsed)				40	A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 10\text{ A}$ , $V_{GS}=0$			1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,		340		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100\text{ V}$		3.26		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	<i>Figure 20</i>		19.2		A
$t_{rr}$	Reverse recovery time	$V_{DD} = 100\text{ V}$		460		ns
$Q_{rr}$	Reverse recovery charge	$di/dt = 100\text{ A}/\mu\text{s}$ , $I_{SD} = 10\text{ A}$		4.42		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$T_J = 150\text{ }^\circ\text{C}$ <i>Figure 20</i>		19.2		A

1. Pulsed: pulse duration = 300 $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220, I<sup>2</sup>PAK, D<sup>2</sup>PAK

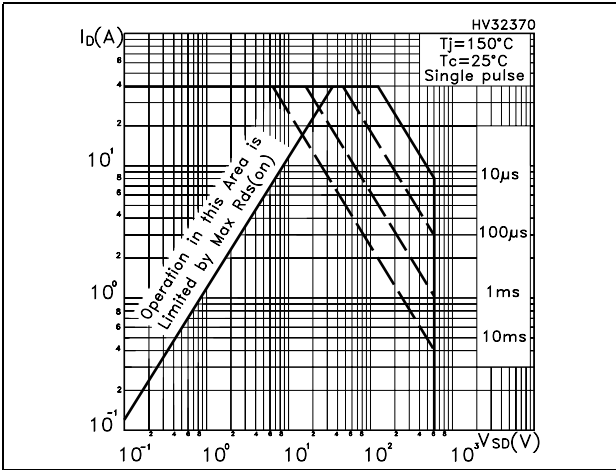


Figure 3. Thermal impedance for TO-220, I<sup>2</sup>PAK, D<sup>2</sup>PAK

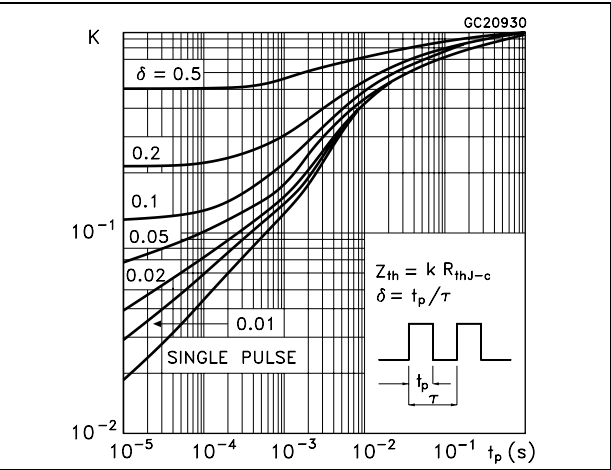


Figure 4. Safe operating area for TO-220FP

Figure 5. Thermal impedance for TO-220FP

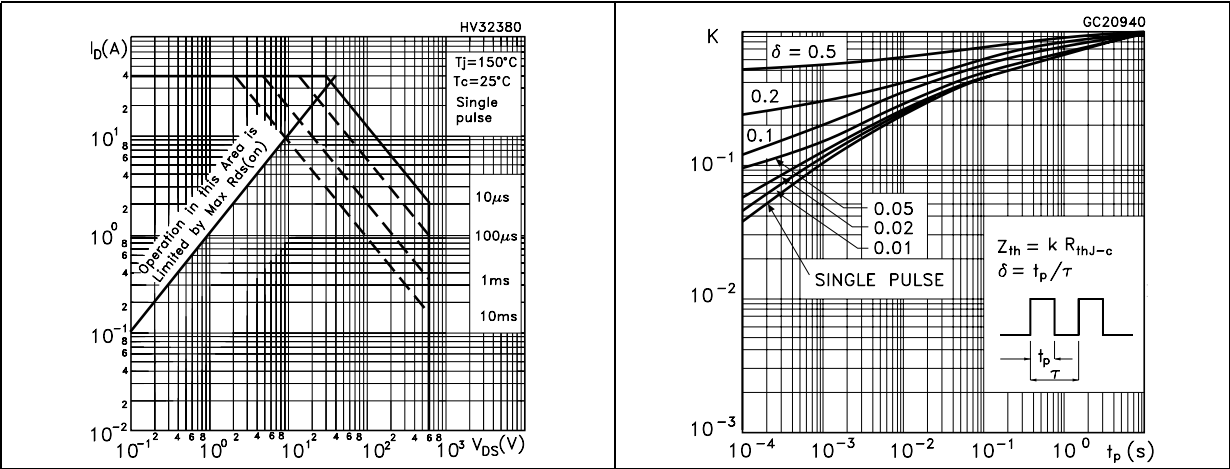


Figure 6. Safe operating area for DPAK, IPAK

Figure 7. Thermal impedance for DPAK, IPAK

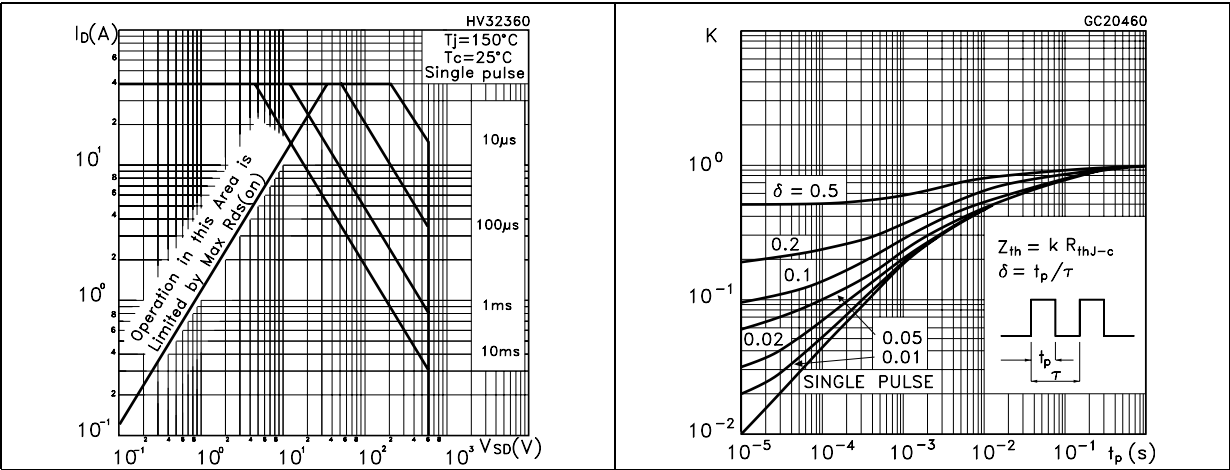


Figure 8. Output characteristics

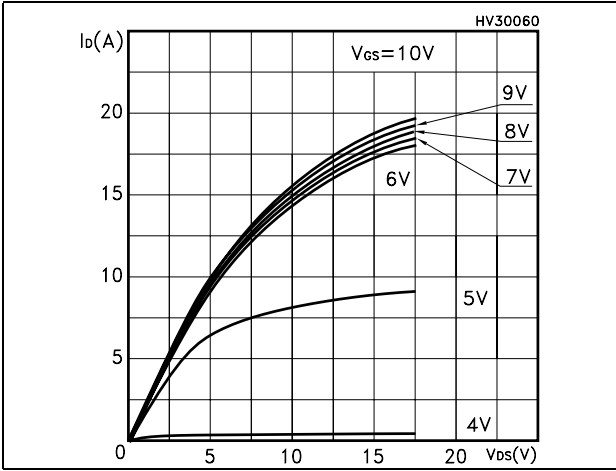


Figure 9. Transfer characteristics

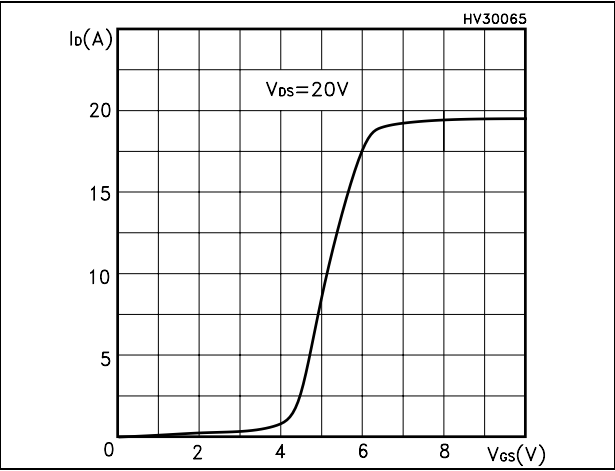


Figure 10. Transconductance

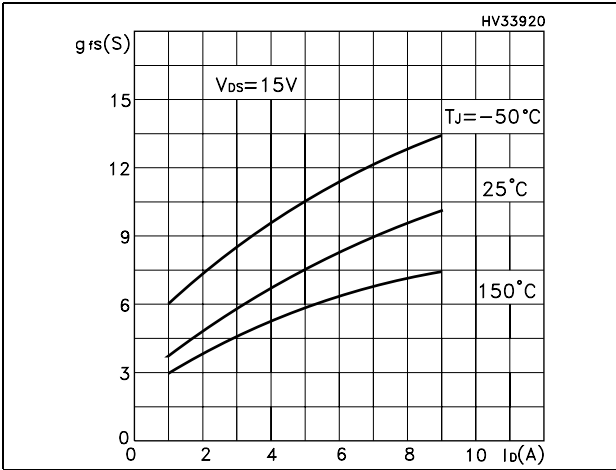


Figure 11. Static drain-source on resistance

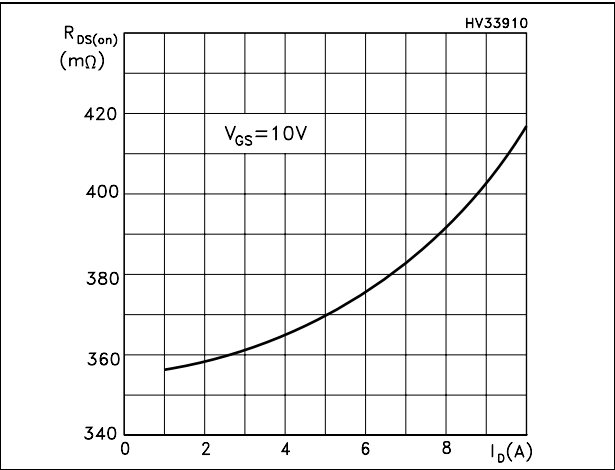


Figure 12. Gate charge vs gate-source voltage Figure 13. Capacitance variations

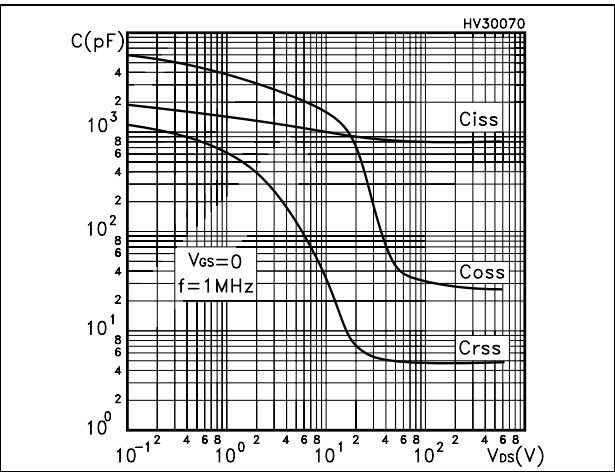
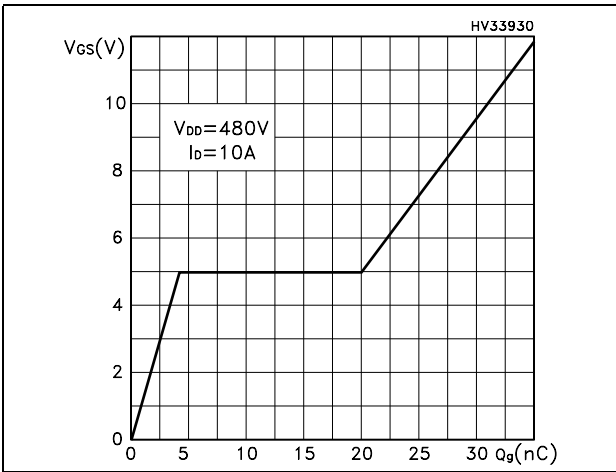


Figure 14. Normalized gate threshold voltage vs temperature

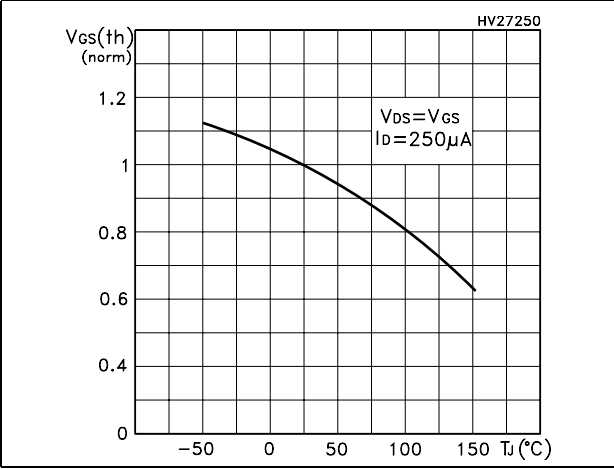


Figure 15. Normalized on resistance vs temperature

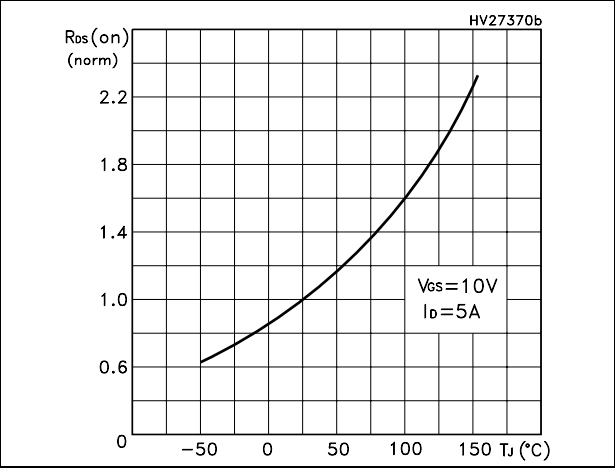


Figure 16. Source-drain diode forward characteristics

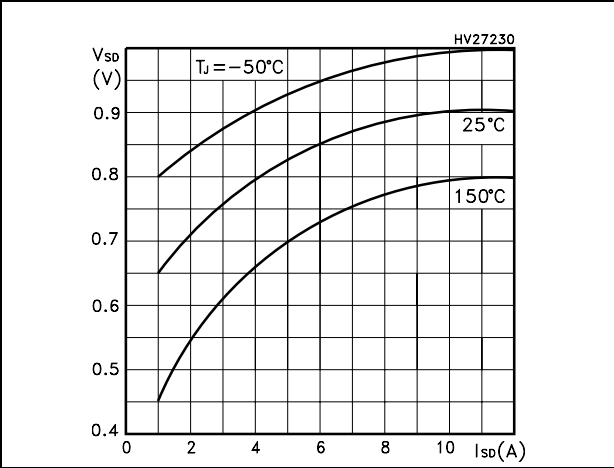
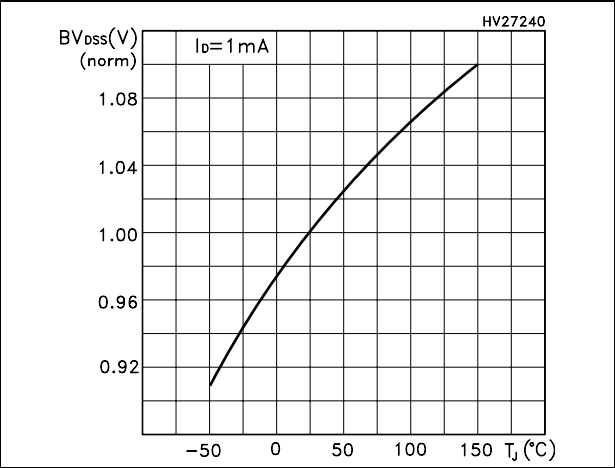
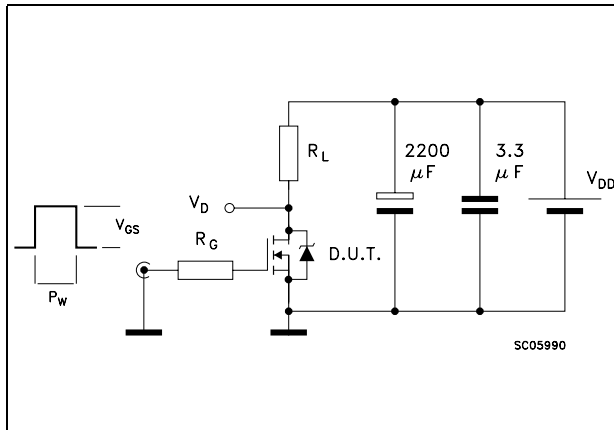


Figure 17. Normalized  $B_{V_{DS}}$  vs temperature

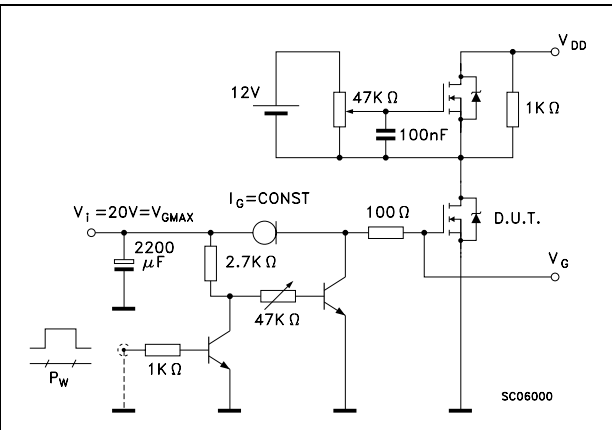


### 3 Test circuits

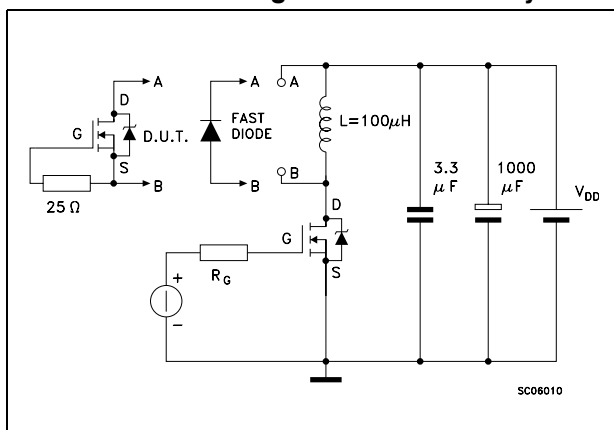
**Figure 18. Switching times test circuit for resistive load**



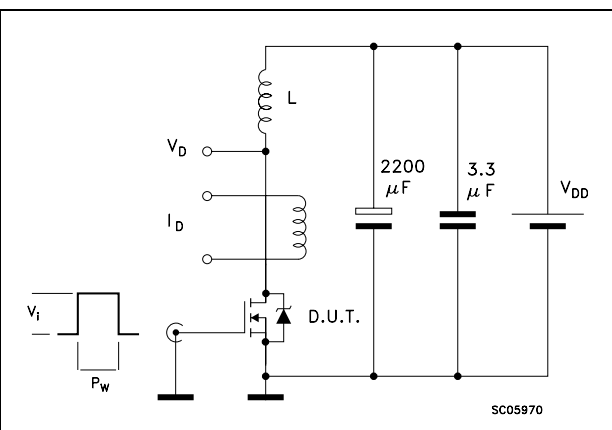
**Figure 19. Gate charge test circuit**



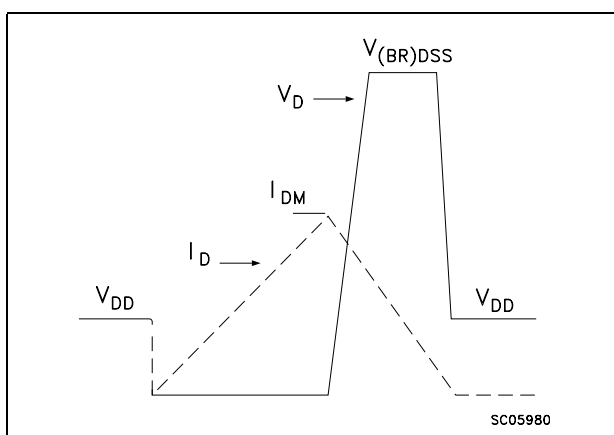
**Figure 20. Test circuit for inductive load switching and diode recovery times**



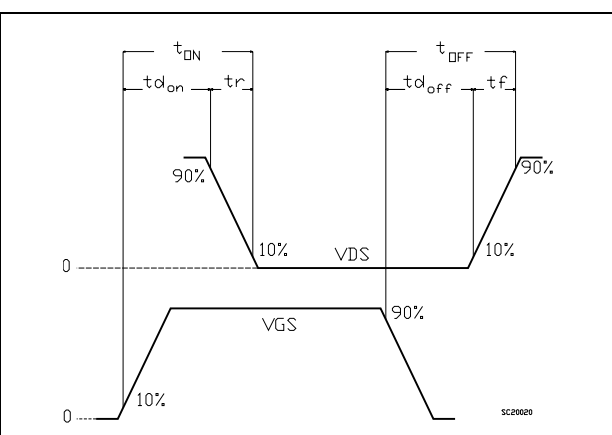
**Figure 21. Unclamped inductive load test circuit**



**Figure 22. Unclamped inductive waveform**



**Figure 23. Switching time waveform**



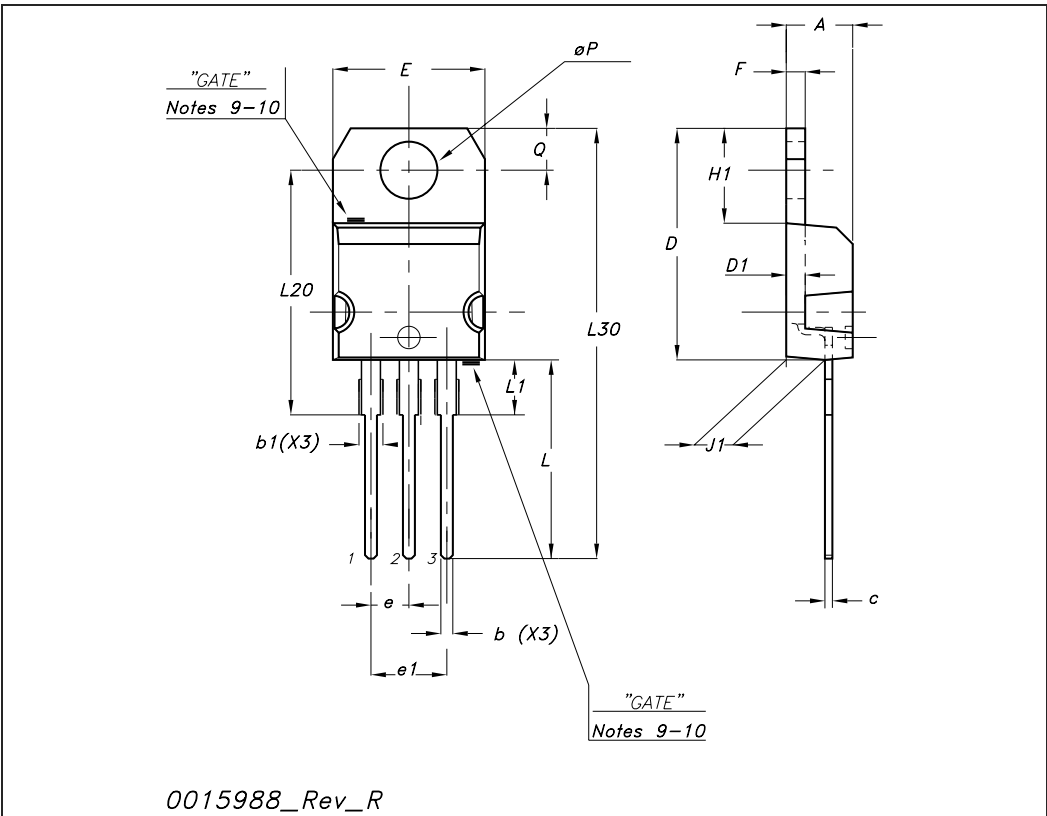


## 4 Package mechanical data

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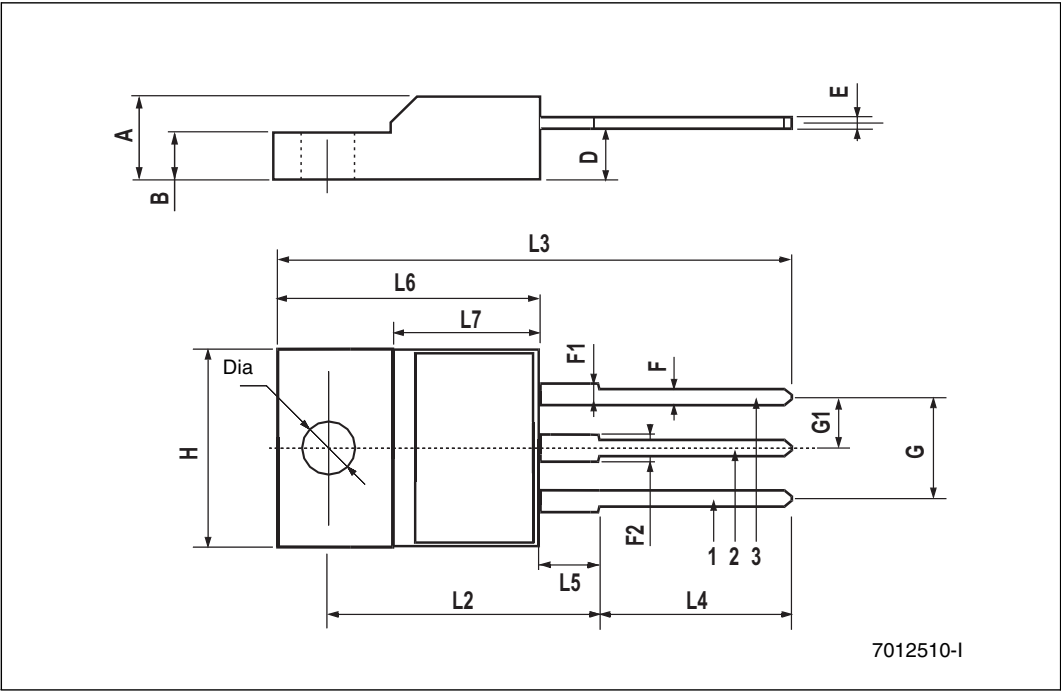
TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
ØP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



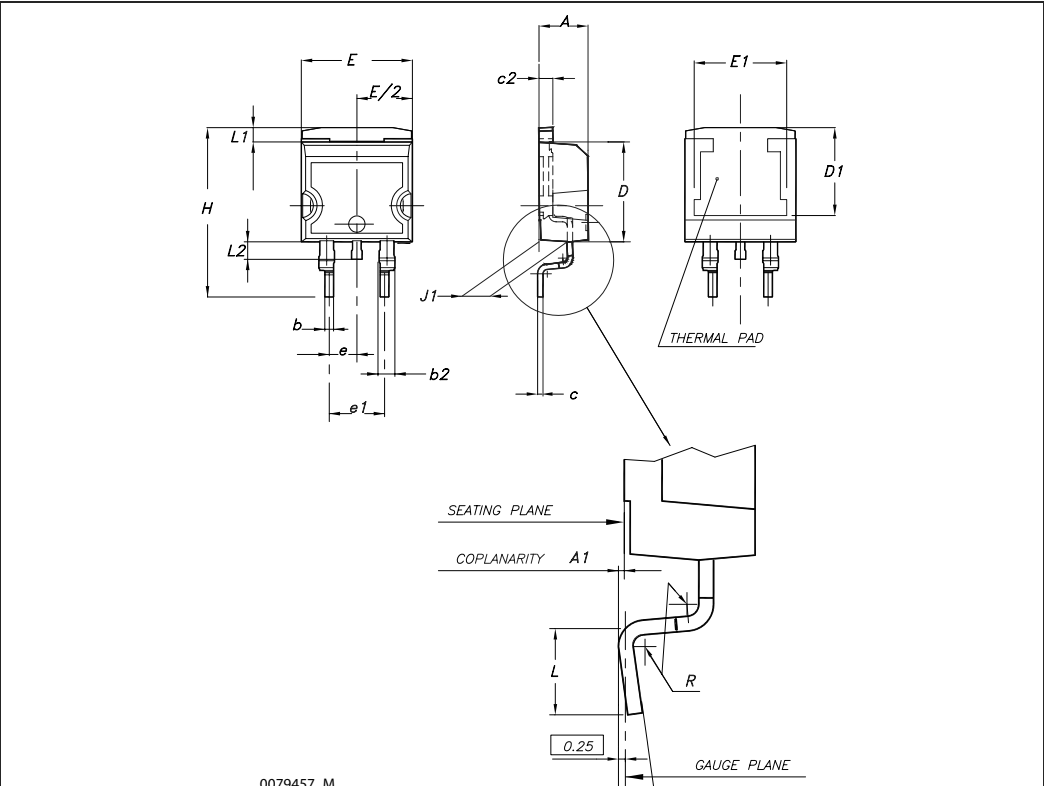
TO-220FP mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.017		0.027
F	0.75		1.00	0.030		0.039
F1	1.15		1.50	0.045		0.067
F2	1.15		1.50	0.045		0.067
G	4.95		5.20	0.195		0.204
G1	2.40		2.70	0.094		0.106
H	10		10.40	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.80		10.60	0.385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.90		16.40	0.626		0.645
L7	9		9.30	0.354		0.366
Dia	3		3.2	0.118		0.126



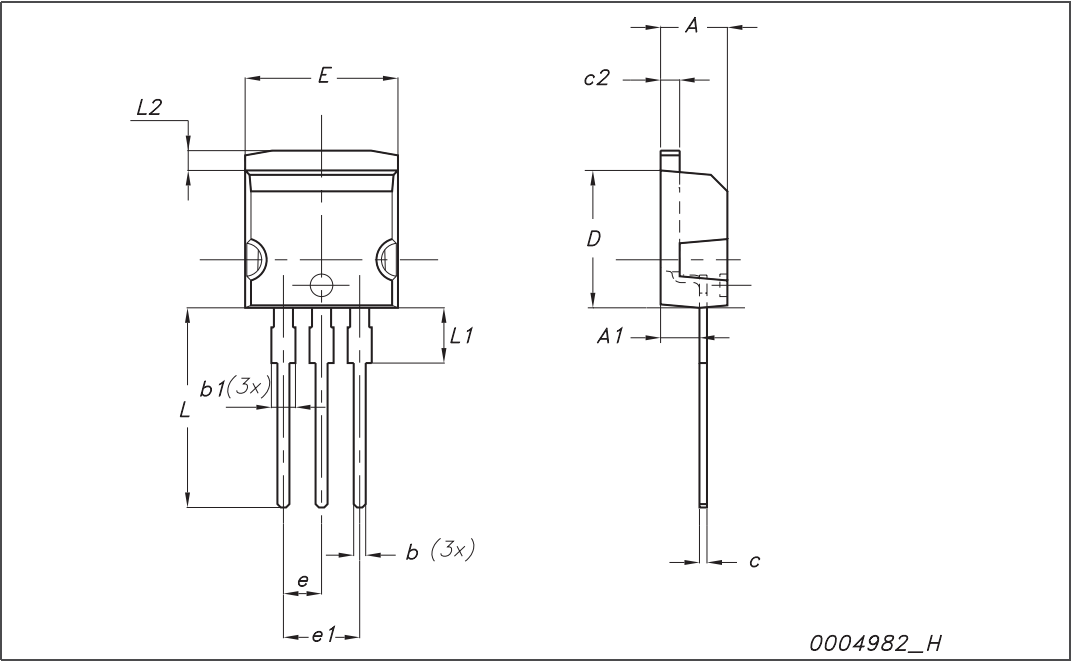
D<sup>2</sup>PAK (TO-263) mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.027		0.037
b2	1.14		1.70	0.045		0.067
c	0.45		0.60	0.017		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50			0.295		
E	10		10.40	0.394		0.409
E1	8.50			0.334		
e		2.54			0.1	
e1	4.88		5.28	0.192		0.208
H	15		15.85	0.590		0.624
J1	2.49		2.69	0.099		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.05		0.055
L2	1.30		1.75	0.051		0.069
R		0.4			0.016	
V2	0°		8°	0°		8°



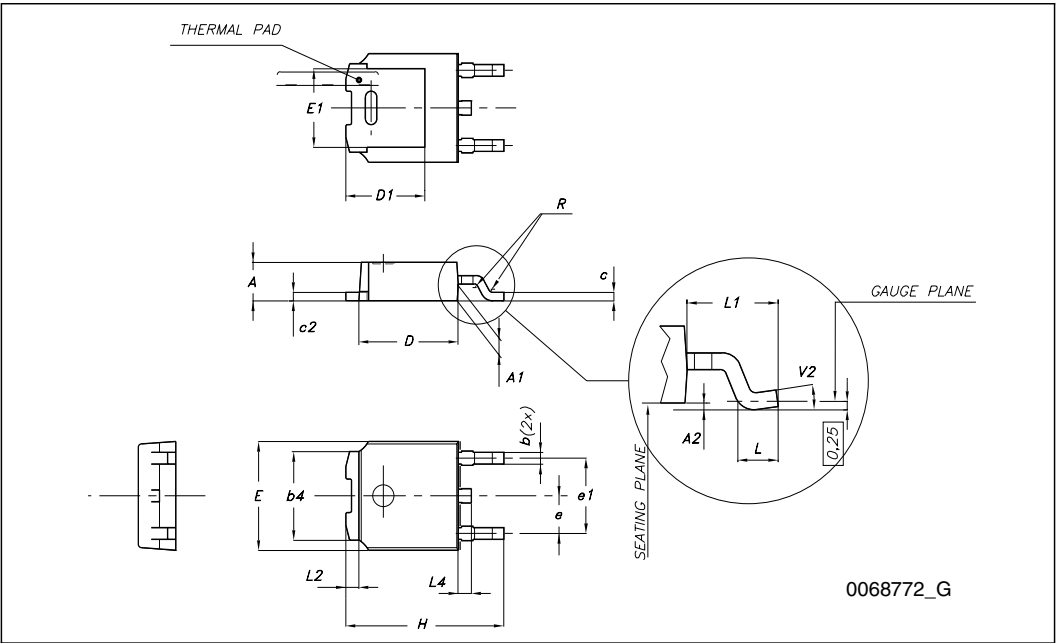
I<sup>2</sup>PAK (TO-262) mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
A1	2.40		2.72	0.094		0.107
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.49		0.70	0.019		0.027
c2	1.23		1.32	0.048		0.052
D	8.95		9.35	0.352		0.368
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
E	10		10.40	0.393		0.410
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L2	1.27		1.40	0.050		0.055



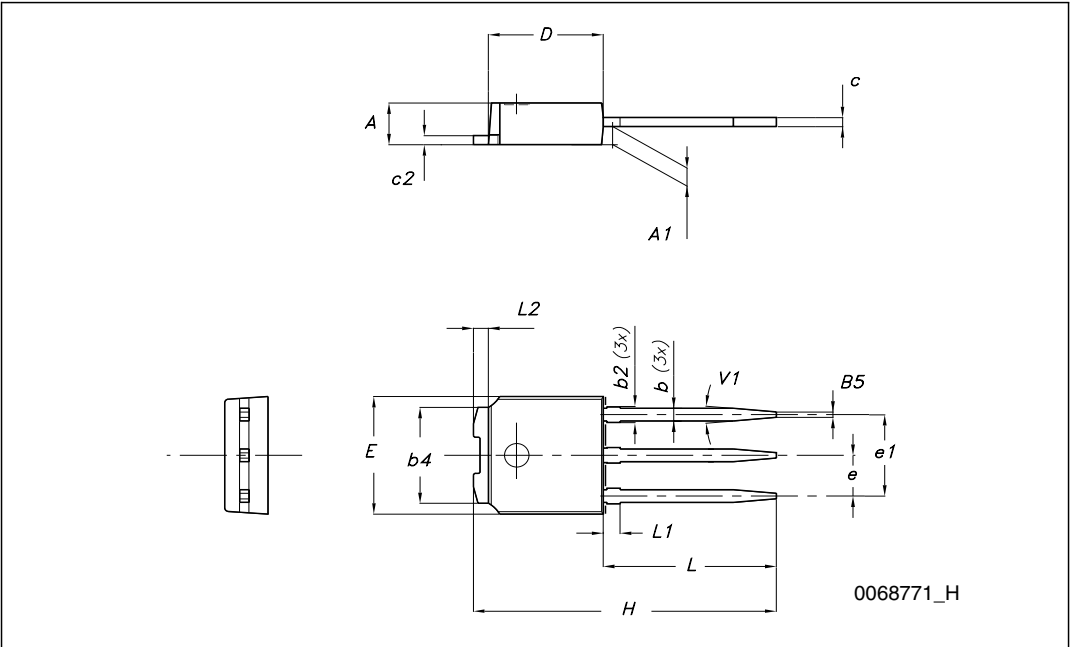
TO-252 (DPAK) mechanical data

DIM.	mm.		
	min.	typ	max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1		
L1		2.80	
L2		0.80	
L4	0.60		1
R		0.20	
V2	0°		8°



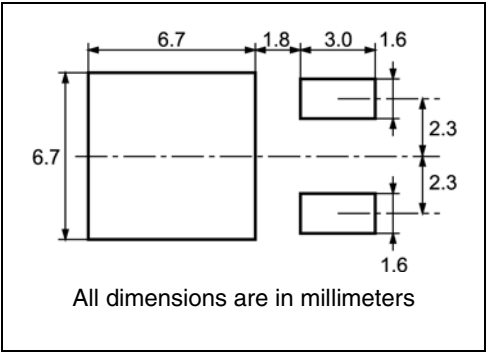
TO-251 (IPAK) mechanical data

DIM.	mm.		
	min.	typ	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
(L1)	0.80		1.20
L2		0.80	
V1		10°	

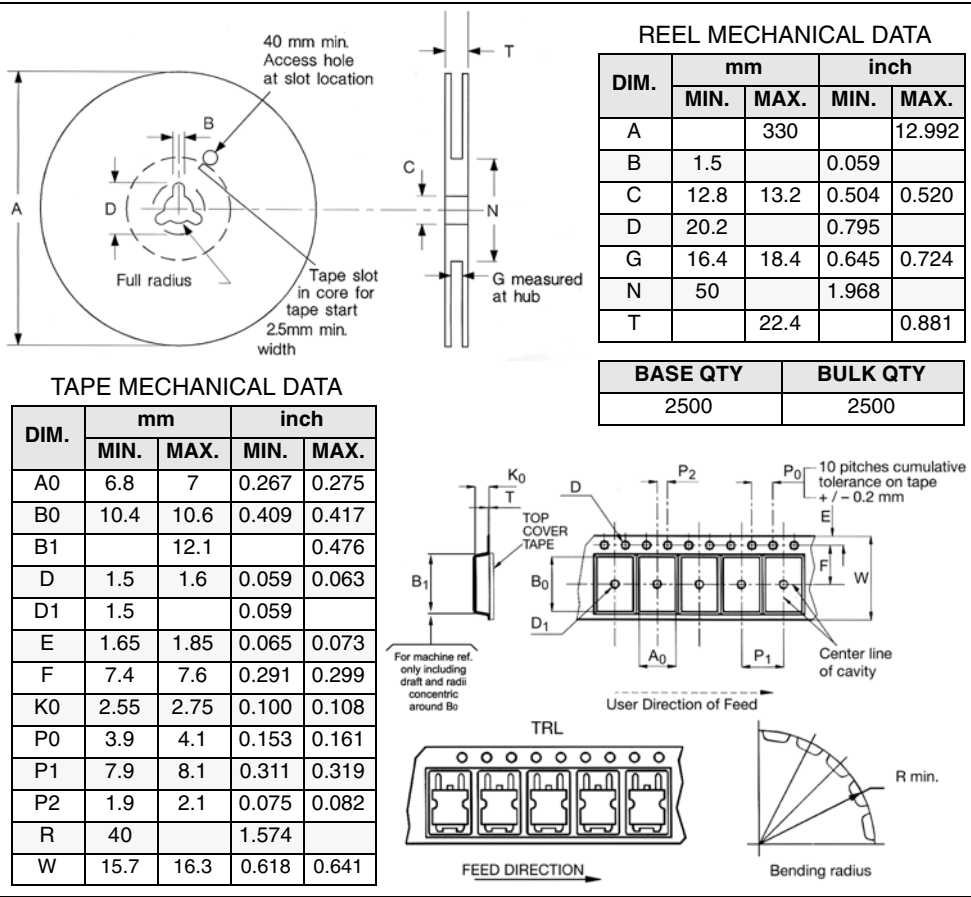


# 5 Packaging mechanical data

## DPAK FOOTPRINT

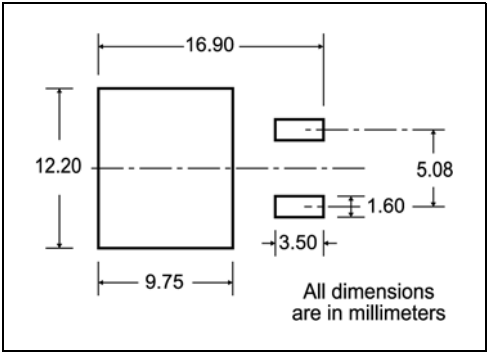


## TAPE AND REEL SHIPMENT

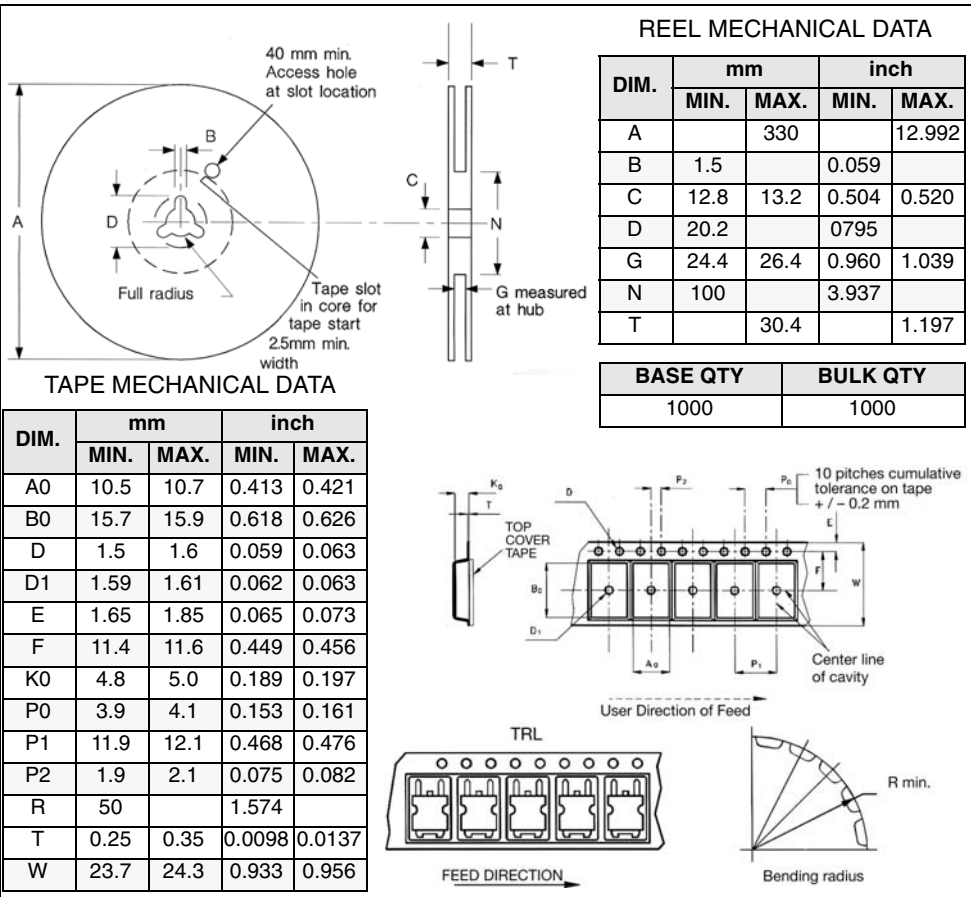




### D<sup>2</sup>PAK FOOTPRINT



### TAPE AND REEL SHIPMENT



\* on sales type

## 6 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
03-Aug-2006	1	First release
14-Nov-2006	2	Complete version
02-Oct-2007	3	<a href="#">Figure 8.: Output characteristics</a> has been updated. Added new package (I <sup>2</sup> PAK)
03-Mar-2008	4	Added new package D <sup>2</sup> PAK
03-Mar-2009	5	<a href="#">Figure 2</a> , <a href="#">Figure 4</a> and <a href="#">Figure 6</a> corrected.

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